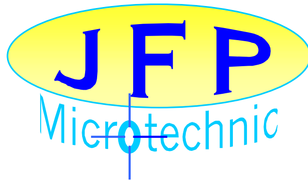
JFP Model PP5

CEFORI Technologies

Manual & Semi Automatic DieBonder / Placer



The die bonder model PP5 is designed for accurate placement of delicate devices on substrate.
It achieves high accuracy placement using adjustable magnification optical device.
The machine provides for single collet vacuum pick and place of die from waffle pack, wafer, Gel-Pak or bulk die media and features adjustable and repeatable subsonic scrub. The placement accuracy is < 5µm.
A robust, and reliable mechanical concept, designed to be external vibration free.
Easy to use, flexible, the PP5-2 requires only minimum training to operate

DIE & SUBSTRATE

- Minimum die size 150*150µm
- Maximum die size 25*25 mm
- Substrate handling, Up to 350 mm.

VISION SYSTEM

- Optical Zoom 10X
- Magnification 180X
- Opt: Digital Zoom 4X
- CCD Color camera high resolution
- TFT monitor 17''
- Target generator
- Lighting
- Direct placement
- 2 references points for auto-centering placement
- Indexed Pick& Place Positionning

XY TABLE

- Motorized X 260mm, Y 120mm, x1µm
- Vibration free
- Motion control with progressive joystick

PARAMETERS & DISPLAY

- LCD display
- Programmable force 10gr to 700 gr
- Opt: Heavy duty Bond Head
- Programmable bond time
- Programmable scrub
- Indexed Pick and Placement mode
- Vacuum selectable

OPTIONS

- Dispenser
- Eutectic / Thermocompresion
- Fast Eutectic Booster: >50°/s
- Stamping
- UV
- Ultrasonic
- Flip chip
- Sorter: Eject sytem for wafer
- Customized work holder
- Hot gaz gun

TECHNICAL SPECIFICATION

Power:	100 / 230VAC 500watt
Vacuum:	70%
Dimensions:	650*820*1450mm
Weight:	90kg.
Compressed Air	6 bar

JFP Microtechnic® is a registered trademark of Cefori

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